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REF ID: A703

PATENT APPLICATION

JUN 21 2001

2800 MAIL ROOM

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Benedict G. Pace Docket No: NH-07A

Serial No.: 09/737,407 Group Art Unit: 2883

Filed: December 15, 2000

Entitled: HIGH DENSITY ELECTRONIC INTERCONNECTION

June 15, 2001

Submission Under 37 CFR 1.98 (a) iii

Assistant Commissioner For Patents
Washington, DC 20231

Sir:

Copies of the following pending applications that may contain material relevant to the above referenced application are submitted herewith in accordance with 37 CFR 1.98 (a) iii.

1. Pace, US Appl'n No. 09/737,408, "Interconnection Method" (12/15/00)
2. Pace, US Appl'n No. 09/745,966, "Inverted Chip bonded Module" (12/22/00)

A supplemental Information Disclosure Statement is also enclosed.

Respectfully submitted,

John F McCormack
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